Single Supply / Low Power / 1024-tap / SPI bus



Preliminary Information

X9111

Single Digitally-Controlled (XDCP™) Potentiometer

FEATURES

- 1024 Resistor Taps 10-Bit Resolution
- SPI Serial Interface for write, read, and transfer operations of the potentiometer
- Wiper Resistance, 40Ω Typical @ 5V
- · Four Non-Volatile Data Registers
- Non-Volatile Storage of Multiple Wiper Positions
- Power On Recall. Loads Saved Wiper Position on Power Up.
- Standby Current < 3µA Max
- V_{CC}: 2.7V to 5.5V Operation
- 100K Ω End to End Resistance
- 100 yr. Data Retention
- Endurance: 100, 000 Data Changes Per Bit Per Register
- 14-Lead TSSOP, 15-Lead CSP (Chip Scale Packaging)
- Low Power CMOS
- Single Supply version of the X9110

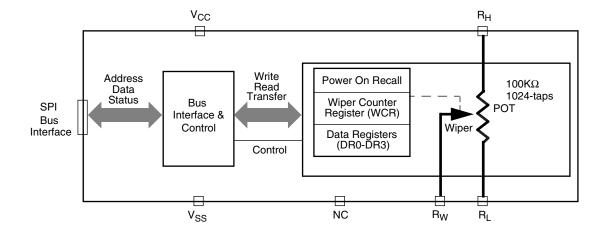
DESCRIPTION

The X9111 integrates a single digitally controlled potentiometer (XDCP) on a monolithic CMOS integrated circuit.

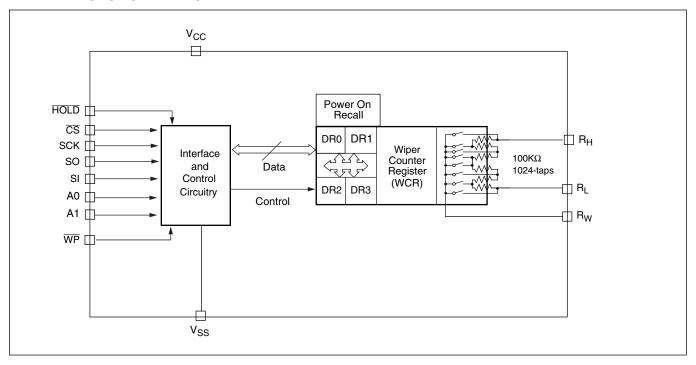
The digital controlled potentiometer is implemented using 1023 resistive elements in a series array. Between each element are tap points connected to the wiper terminal through switches. The position of the wiper on the array is controlled by the user through the SPI bus interface. The potentiometer has associated with it a volatile Wiper Counter Register (WCR) and four non-volatile Data Registers that can be directly written to and read by the user. The contents of the WCR controls the position of the wiper on the resistor array though the switches. Powerup recalls the contents of the default data register (DR0) to the WCR.

The XDCP can be used as a three-terminal potentiometer or as a two terminal variable resistor in a wide variety of applications including control, parameter adjustments, and signal processing.

FUNCTIONAL DIAGRAM



DETAILED FUNCTIONAL DIAGRAM



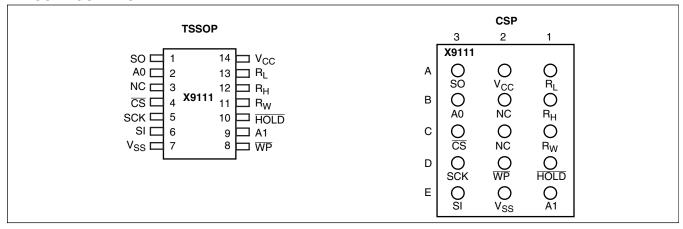
CIRCUIT LEVEL APPLICATIONS

- · Vary the gain of a voltage amplifier
- Provide programmable dc reference voltages for comparators and detectors
- · Control the volume in audio circuits
- Trim out the offset voltage error in a voltage amplifier circuit
- Set the output voltage of a voltage regulator
- Trim the resistance in Wheatstone bridge circuits
- Control the gain, characteristic frequency and Q-factor in filter circuits
- Set the scale factor and zero point in sensor signal conditioning circuits
- Vary the frequency and duty cycle of timer ICs
- Vary the dc biasing of a pin diode attenuator in RF circuits
- Provide a control variable (I, V, or R) in feedback circuits

SYSTEM LEVEL APPLICATIONS

- · Adjust the contrast in LCD displays
- Control the power level of LED transmitters in communication systems
- Set and regulate the DC biasing point in an RF power amplifier in wireless systems
- Control the gain in audio and home entertainment systems
- Provide the variable DC bias for tuners in RF wireless systems
- Set the operating points in temperature control systems
- Control the operating point for sensors in industrial systems
- Trim offset and gain errors in artificial intelligent systems

PIN CONFIGURATION



PIN ASSIGNMENTS

Pin (TSSOP)	Pin (CSP)	Symbol	Function
1	А3	SO	Serial Data Output
2	B3	A0	Device Address
3	B2, C2	NC	No Connect
4	C3	CS	Chip Select
5	D3	SCK	Serial Clock
6	E3	SI	Serial Data Input
7	E2	V _{SS}	System Ground
8	D2	WP	Hardware Write Protect
9	E1	A1	Device Address
10	D1	HOLD	Device Select. Pause the Serial Bus
11	C1	R _W	Wiper Terminal of the Potentiometer
12	B1	R _H	High Terminal of the Potentiometer
13	A1	RL	Low Terminal of the Potentiometer
14	A2	V _{CC}	System Supply Voltage

PIN DESCRIPTIONS

Bus Interface Pins

SERIAL OUTPUT (SO)

SO is a serial data output pin. During a read cycle, data is shifted out on this pin. Data is clocked out by the falling edge of the serial clock.

SERIAL INPUT (SI)

SI is the serial data input pin. All opcodes, byte addresses and data to be written to the pots and pot registers are input on this pin. Data is latched by the rising edge of the serial clock.

SERIAL CLOCK (SCK)

The SCK input is used to clock data into and out of the X9111.

HOLD (HOLD)

HOLD is used in conjunction with the $\overline{\text{CS}}$ pin to select the device. Once the part is selected and a serial sequence is underway, $\overline{\text{HOLD}}$ may be used to pause the serial communication with the controller without resetting the serial sequence. To pause, $\overline{\text{HOLD}}$ must be brought LOW while SCK is LOW. To resume communication, $\overline{\text{HOLD}}$ is brought HIGH, again while SCK is LOW. If the pause feature is not used, $\overline{\text{HOLD}}$ should be held HIGH at all times.

DEVICE ADDRESS (A₀, A₁)

The address inputs are used to set the 8-bit slave address. A match in the slave address serial data stream must be made with the address input (A1–A0) in order to initiate communication with the X9111.

CHIP SELECT (CS)

When \overline{CS} is HIGH, the X9111 is deselected and the SO pin is at high impedance, and (unless an internal write cycle is underway) the device will be in the standby state. \overline{CS} LOW enables the X9111, placing it in the active power mode. It should be noted that after a power-up, a HIGH to LOW transition on \overline{CS} is required prior to the start of any operation.

HARDWARE WRITE PROTECT INPUT (WP)

The $\overline{\text{WP}}$ pin when LOW prevents nonvolatile writes to the Data Registers.

Potentiometer Pins

R_H, R_L

The R_H and R_L pins are equivalent to the terminal connections on a mechanical potentiometer.

R_W

The wiper pin is equivalent to the wiper terminal of a mechanical potentiometer.

Bias Supply Pins

System Supply Voltage (V_{CC}) and Supply Ground (V_{SS})

The V_{CC} pin is the system supply voltage. The V_{SS} pin is the system ground.

Other Pins

No Connect (NC)

Pin should be left open. This pin is used for Xicor manufacturing and test purposes.

PRINCIPLES OF OPERATION

DEVICE DESCRIPTION

Serial Interface

The X9111 supports the SPI interface hardware conventions. The device is accessed via the SI input with data clocked-in on the rising SCK. \overline{CS} must be LOW and the \overline{HOLD} and \overline{WP} pins must be HIGH during the entire operation.

The SO and SI pins can be connected together, since they have three state outputs. This can help to reduce system pin count.

Array Description

The X9111 is comprised of a resistor array (see Figure 1). The array contains the equivalent of 1023 discrete resistive segments that are connected in series. The physical ends of each array are equivalent to the fixed terminals of a mechanical potentiometer (R_H and R_L inputs).

At both ends of each array and between each resistor segment is a CMOS switch connected to the wiper (R_W) output. Within the individual array only one switch may be turned on at a time.

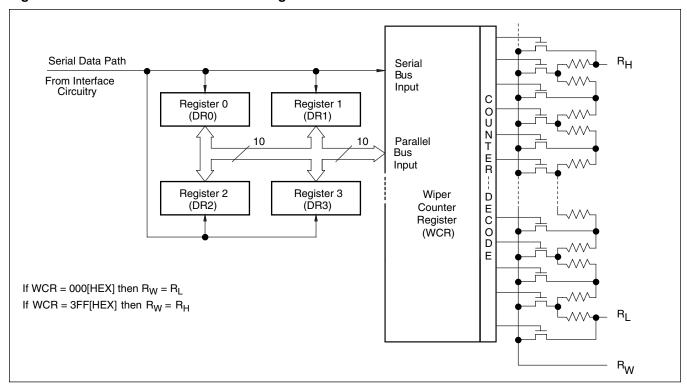


Figure 1. Detailed Potentiometer Block Diagram

These switches are controlled by a Wiper Counter Register (WCR). The 10-bits of the WCR (WCR[9:0]) are decoded to select, and enable, one of 1024 switches.

Wiper Counter Register (WCR)

The X9111 contains a Wiper Counter Register (see Table 1) for the XDCP potentiometer. The WCR is equivalent to a serial-in, parallel-out register/counter with its outputs decoded to select one of 1024 switches along its resistor array. The contents of the WCR can be altered in one of three ways: (1) it may be written directly by the host via the write Wiper Counter Register instruction (serial load); (2) it may be written indirectly by transferring the contents of one of four associated Data Registers via the XFR Data Register; (3) it is loaded with the contents of its Data Register zero (DR0) upon power-up.

The Wiper Counter Register is a volatile register; that is, its contents are lost when the X9111 is powered-down. Although the register is automatically loaded with the value in R0 upon power-up, this may be different from the value present at power-down. Power-up guidelines are recommended to ensure proper loadings of the R0 value into the WCR.

Data Registers (DR3 to DR0)

The potentiometer has four 10-bit non-volatile Data Registers. These can be read or written directly by the host. Data can also be transferred between any of the four Data Registers and the Wiper Counter Register. All operations changing data in one of the Data Registers is a nonvolatile operation and will take a maximum of 10ms.

If the application does not require storage of multiple settings for the potentiometer, the Data Registers can be used as regular memory locations for system parameters or user preference data.

A DR[9:0] is used to store one of the 1024 wiper position (0 \sim 1023). Table 2.

Status Register (SR)

This 1-bit status register is used to store the system status (see Table 3).

WIP: Write In Progress status bit, read only.

- When WIP=1, indicates that high-voltage write cycle is in progress.
- When WIP=0, indicates that no high-voltage write cycle is in progress.

Table 1. Wiper Latch, WL (10-bit), WCR9-WCR0: Used to store the current wiper position (Volatile, V)

WCR9	WCR8	WCR7	WCR6	WCR5	WCR4	WCR3	WCR2	WCR1	WCR0
V	V	V	٧	٧	V	٧	V	V	V
(MSB)									(LSB)

Table 2. Data Register, DR (10-bit), Bit 9-Bit 0: Used to store wiper positions or data (Non-Volatile, NV)

Е	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
	ΛΛ	NV								
N	1SB									LSB

Table 3. Status Register, SR (1-bit)

WIP (LSB)

DEVICE INSTRUCTIONS

Identification Byte (ID and A)

The first byte sent to the X9111 from the host, following a \overline{CS} going HIGH to LOW, is called the Identification Byte. The most significant four bits of the slave address are a device type identifier. The ID[3:0] bits is the device ID for the X9111; this is fixed as 0101[B] (refer to Table 4).

The A1-A0 bits in the ID byte are the internal slave address. The physical device address is defined by the state of the A1-A0 input pins. The slave address is externally specified by the user. The X9111 compares the serial data stream with the address input state; a

successful compare of the address bits is required for the X9111 to successfully continue the command sequence. Only the device whose slave address matches the incoming device address sent by the master executes the instruction. The A1–A0 inputs can be actively driven by CMOS input signals or tied to V_{CC} or V_{SS} . The R/W bit is used to set the device to either read or write mode.

Instruction Byte and Register Selection

The next byte sent to the X9111 contains the instruction and register pointer information. The three most significant bits are used provide the instruction opcode (I[2:0]). The RB and RA bits point to one of the four registers. The format is shown in Table 5.

Table 4. Identification Byte Format

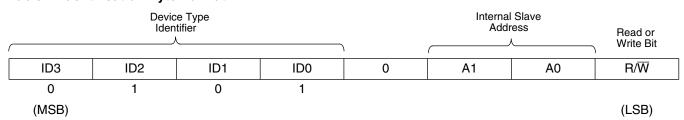
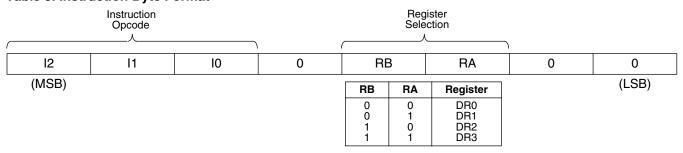


Table 5. Instruction Byte Format



REV 1.1.15 5/9/03

Five of the seven instructions are four bytes in length. These instructions are:

- Read Wiper Counter Register read the current wiper position of the selected pot,
- Write Wiper Counter Register change current wiper position of the selected pot,
- Read Data Register read the contents of the selected data register;
- Write Data Register write a new value to the selected data register.
- Read Status This command returns the contents of the WIP bit which indicates if the internal write cycle is in progress.

The basic sequence of the four byte instructions is illustrated in Figure 3. These four-byte instructions exchange data between the WCR and one of the Data Registers. A transfer from a Data Register to a WCR is essentially a write to a static RAM, with the static RAM controlling the wiper position. The response of the wiper to this action will be delayed by t_{WRL}. A transfer from the WCR (current wiper position), to a Data Register is a write to nonvolatile memory and takes a minimum of t_{WR} to complete. The transfer can occur between the potentiometer and one of its associated registers. The Read Status Register instruction is the only unique format (see Figure 4).

Two instructions require a two-byte sequence to complete (see Figure 2). These instructions transfer data between the host and the X9111; either between

the host and one of the Data Registers or directly between the host and the Wiper Counter Register. These instructions are:

- XFR Data Register to Wiper Counter Register –
 This transfers the contents of one specified Data
 Register to the associated Wiper Counter Register.
- XFR Wiper Counter Register to Data Register –
 This transfers the contents of the specified Wiper
 Counter Register to the specified associated Data
 Register.

See Instruction format for more details.

Write in Process (WIP bit)

The contents of the Data Registers are saved to nonvolatile memory when the \overline{CS} pin goes from LOW to HIGH after a complete write sequence is received by the device. The progress of this internal write operation can be monitored by a Write In Process bit (WIP). The WIP bit is read with a Read Status command (see Figure 4).

Power Up and Down Requirements

There are no restrictions on the power-up condition of V_{CC} and the voltages applied to the potentiometer pins provided that the V_{CC} is always more positive than or equal to the voltages at R_H , R_L , and R_W , i.e., $V_{CC} \ge R_H$, R_L , R_W . There are no restrictions on the power-down condition. However, the datasheet parameters for the DCP do not apply until 1millisecond after V_{CC} reaches its final value.

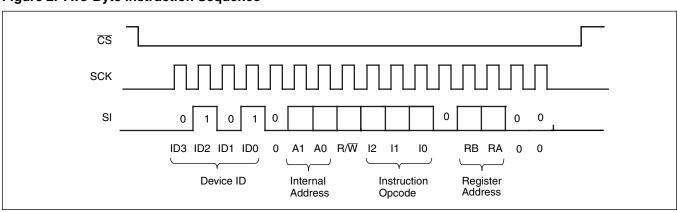


Figure 2. Two-Byte Instruction Sequence

Figure 3. Four-Byte Instruction Sequence (Write or Read for WCR or Data Registers)

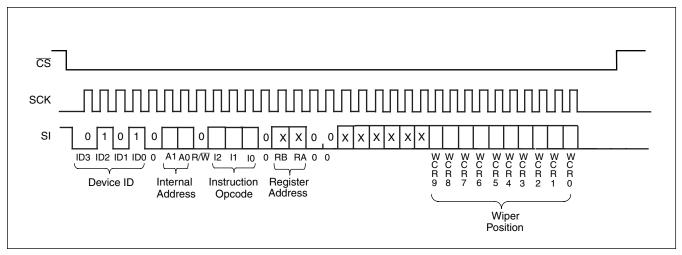


Figure 4. Four-Byte Instruction Sequence (Read Status Registers)

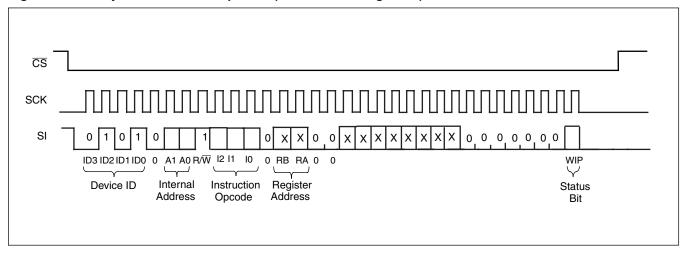


Table 6. Instruction Set

				In	struc	tion S	et			
Instruction	R/W	l ₃	l ₂	l ₁	0	RB	RA	0	0	Operation
Read Wiper Counter Register	1	1	0	0	0	0	0	0	0	Read the contents of the Wiper Counter Register
Write Wiper Counter Register	0	1	0	1	0	0	0	0	0	Write new value to the Wiper Counter Register
Read Data Register	1	1	0	1	0	1/0	1/0	0	0	Read the contents of the Data Register pointed to RB-RA
Write Data Register	0	1	1	0	0	1/0	1/0	0	0	Write new value to the Data Register pointed to RB-RA
XFR Data Register to Wiper Counter Register	1	1	1	0	0	1/0	1/0	0	0	Transfer the contents of the Data Register pointed to by RB-RA to the Wiper Counter Register
XFR Wiper Counter Register to Data Register	0	1	1	1	0	1/0	1/0	0	0	Transfer the contents of the Wiper Counter Register to the Data Register pointed to by RB-RA
Read Status (WIP bit)	1	0	1	0	0	0	0	0	1	Read the status of the internal write cycle, by checking the WIP bit (read status register).

Note: (1) 1/0 = data is one or zero

INSTRUCTION FORMAT

Read Wiper Counter Register (WCR)

	CS	De I	evic den	e Ty tifie	pe r			evice resse				ictic ode			Reg ddre			(Wip nt by)	(tion on)	CS
F	alling Edge	0	1	0	1	0	A1	A0	$R/\overline{W}=1$	1	0	0	0	0	0	0	0	х	х	х	х	х	х	WCR9	&CR®	WCR7	SCR6	WCR5	WCR4	W C R 3	WCR2	W C R 1	WCR0	Rising Edge

Write Wiper Counter Register (WCR)

CS	D	evic Iden	e Ty tifie	pe r			evice resse		lr	nstru Opc	uctic			Reg ddre					Wip nt b				n SI))						tion er or)	CS
Falling Edge	0	1	0	1	0	A1	A0	$R/\overline{W} = 0$	1	0	1	0	0	0	0	0	х	х	х	х	х	х	W C R 9	WCR8	WCR7	SCR6	WCR5	W C R 4	W C R 3	W C R 2	W C R 1	WCRo	Rising Edge

Read Data Register (DR)

CS		evic den					evice Iresse				uctic			Regi: ddre		s						tion on	SO)	(Wip)	CS
Falling Edge	0	1	0	1	0	A1	Α0	R/ W= 1	1	0	1	0	RB	RA	0	0	х	х	х	Х	х	х	WCR9	WCR8	WCR7	W C R 6	WCR5	W C R 4	WCR3	W C R 2	W C R 1	WCR0	Rising Edge

Write Data Register (DR)

		evic Ider			,	De [,] Addr	vice esse	:S			uctio			Regi ddre					er F								Posit y Ma					CS	AGE	
CS Falling Edge	0	1	0	1	0	A1	A0	$R/\overline{W}=0$	1	1	0	0	RB	RA	0	0	х	x	x	х	x	х	1	C R	WCR6	WCR 5	W C R 4	W C R 3	W C R 2	W C R 1	WCR0	Rising Edge	HIGH-VOLT WRITE CY	

Transfer Data Register (DR) to Wiper Counter Register (WCR)

<u>cs</u>		evice den					evice dress				uctic code			Regi ddre			<u>CS</u>
Falling Edge	0	1	0	1	0	A1	A0	R/ W= 1	1	1	0	0	RB	RA	0	0	Rising Edge

Transfer Wiper Counter Register (WCR) to Data Register (DR)

		evice Type Devidentifier Addre	vice esse	es			uctic code			Regis Addres			<u>cs</u>					
CS Falling Edge	0	1	0	1	0	A1	A0	$R/\overline{W} = 0$	1	1	1	0	RB	RA	0	0	Rising Edge	HIGH-VOLTAGE WRITE CYCLE

Read Status Register (SR)

		evice den			,		vice esse			stru Opc					iste esse			(Se			s Da ave		SO)			(Se			is D lave	ata e on	SC))	CS
CS Falling Edge	0	1	0	1	0	A1	A0	$R/\overline{W}=1$	0	1	0	0	0	0	0	1	х	х	х	х	х	х	Х	х	0	0	0	0	0	0	0	WIP	Rising Edge

Notes: (1) "A0 and A1": stand for the device address sent by the master.

- (2) WCRx refers to wiper position data in the Wiper Counter Register
- (3) "X": Don't Care.

ABSOLUTE MAXIMUM RATINGS

Temperature under bias65°C to +135°C
Storage temperature65°C to +150°C
Voltage on SCK any address input
with respect to V _{SS} –1V to +7V
$\Delta V = (VH-VL) \dots 5V$
Lead temperature (soldering, 10 seconds) 300°C
I _W (10 seconds)±6mA

COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only; the functional operation of the device (at these or any other conditions above those listed in the operational sections of this specification) is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

Temp	Min.	Max.
Commercial	0°C	+70°C
Industrial	−40°C	+85°C

Device	Supply Voltage (V _{CC}) Limits	
X9111	5V ±10%	
X9111-2.7	2.7V to 5.5V	

ANALOG CHARACTERISTICS (Over recommended industrial operation conditions unless otherwise stated.)

		Limits				
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
R _{TOTAL}	End to End Resistance		100		kΩ	
	End to End Resistance Tolerance			±20	%	
	Power Rating			50	mW	25°C, each pot
I _W	Wiper Current			±3	mA	
R _W	Wiper Resistance		40	110	Ω	Wiper Current = \pm 50 μ A, V_{CC} = 5 V
			150	300	Ω	Wiper Current = \pm 50 μ A, V_{CC} = 3 V
V _{TERM}	Voltage on any R _H or R _L Pin	V_{SS}		5	V	V _{SS} = 0V
	Noise		-120		dBV	Ref: 1V
	Resolution		1.6		%	
	Absolute Linearity ⁽¹⁾			±1	MI ⁽³⁾	R _{w(n)(actual)} – R _{w(n)(expected)} , where n=8 to 1006
			±1.5	±2.0	MI ⁽³⁾	$R_{w(n)(actual)} - R_{w(n)(expected)}^{(6)}$
	Relative Linearity ⁽²⁾			±0.5	MI ⁽³⁾	$R_{w(m+1)} - [R_{w(m)} + MI]$, where m=8 to 1006
			±0.5	±1.0	MI ⁽³⁾	$R_{w(m+1)} - [R_{w(m)} + MI]^{(6)}$
	Temperature Coefficient of R _{TOTAL}		±300		ppm/°C	
	Ratiometric Temp. Coefficient			20	ppm/°C	
C _H /C _L /C _W	Potentiometer Capacitancies		10/10/25		pF	See Macro model

Notes: (1) Absolute linearity is utilized to determine actual wiper voltage versus expected voltage as determined by wiper position when used as a potentiometer.

- (2) Relative linearity is utilized to determine the actual change in voltage between two successive tap positions when used as a potentiometer. It is a measure of the error in step size.
- (3) MI = RTOT / 1023 or $(R_H R_L) / 1023$, single pot
- (4) n = 0, 1, 2, ..., 1023; m = 0, 1, 2, ..., 1022.
- (5) ESD Rating on RH, RL, RW pins is 1.5KV (HBM, 1.0µA leakage maximum), ESD rating on all other pins is 2.0KV.

D.C. OPERATING CHARACTERISTICS (Over the recommended operating conditions unless otherwise specified.)

			Limits			
Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
I _{CC1}	V _{CC} supply current (active)		μ A f_{SCK} = 2.5 MHz, SO = C Other Inputs = V _{SS}		f_{SCK} = 2.5 MHz, SO = Open, V_{CC} =5.5V Other Inputs = V_{SS}	
I _{CC2}	V _{CC} supply current (nonvolatile write)	current 1 5 mA f _{SCK} = 2.5MHz, write) Other Inputs = V		f_{SCK} = 2.5MHz, SO = Open, V_{CC} =5.5V Other Inputs = V_{SS}		
I _{SB}	V _{CC} current (standby)			3	μΑ	$SCK = SI = V_{SS}$, Addr. = V_{SS} , $\overline{CS} = V_{CC} = 5.5V$
ILI	Input leakage current			10	μΑ	$V_{IN} = V_{SS}$ to V_{CC}
I _{LO}	Output leakage current			10	μΑ	$V_{OUT} = V_{SS}$ to V_{CC}
V _{IH}	Input HIGH voltage	V _{CC} x 0.7		V _{CC} + 1	٧	
V _{IL}	Input LOW voltage	-1		V _{CC} x 0.3	٧	
V _{OL}	Output LOW voltage			0.4	V	I _{OL} = 3mA
V _{OL}	Output LOW voltage	V _{CC} - 0.8			V	$I_{OH} = -1 \text{mA}, V_{CC} \ge +3 \text{V}$
V _{OL}	Output LOW voltage	V _{CC} - 0.4			٧	$I_{OH} = -0.4$ mA, $V_{CC} \le +3$ V

ENDURANCE AND DATA RETENTION

Parameter	Min.	Units
Minimum Endurance	100,000	Data changes per bit per register
Data Retention	100	years

CAPACITANCE

Symbol	nbol Test		Units	Test Conditions
C _{IN/OUT} ⁽⁶⁾	T ⁽⁶⁾ Input/Output capacitance (SI)		pF	V _{OUT} = 0V
C _{OUT} ⁽⁶⁾	Output capacitance (SO)		pF	V _{OUT} = 0V
C _{IN} ⁽⁶⁾			pF	$V_{IN} = 0V$

POWER-UP TIMING

Symbol	Parameter	Min.	Max.	Units
t _r V _{CC} ⁽⁶⁾	V _{CC} power-up rate	0.2	50	V/ms
t _{PUR} ⁽⁷⁾	Power-up to initiation of read operation		1	ms
t _{PUW} ⁽⁷⁾	Power-up to initiation of write operation		50	ms

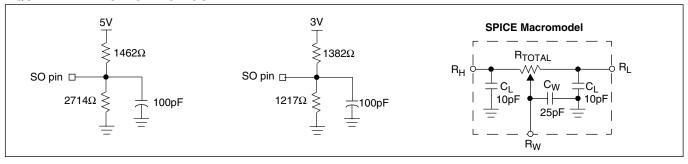
Notes: (6) This parameter is not 100% tested

⁽⁷⁾ t_{PUR} and t_{PUW} are the delays required from the time the (last) power supply (V_{CC}-) is stable until the specific instruction can be issued. These parameters are not 100% tested.

A.C. TEST CONDITIONS

Input pulse levels	V _{CC} x 0.1 to V _{CC} x 0.9
Input rise and fall times	10ns
Input and output timing level	V _{CC} x 0.5

EQUIVALENT A.C. LOAD CIRCUIT



AC TIMING

Symbol	Parameter	Min.	Max.	Units
f _{SCK}	SSI/SPI clock frequency		2.0	MHz
t _{CYC}	t _{CYC} SSI/SPI clock cycle time			ns
t _{WH}	SSI/SPI clock high time	150		ns
t _{WL}	SSI/SPI clock low time	150		ns
t _{LEAD}	Lead time	150		ns
t _{LAG}	Lag time	150		ns
t _{SU}	SI, SCK, HOLD and CS input setup time	50		ns
t _H	SI, SCK, HOLD and CS input hold time	50		ns
t _{RI}	SI, SCK, HOLD and CS input rise time		50	ns
t _{Fl}	SI, SCK, HOLD and CS input fall time		50	ns
t _{DIS}	SO output disable time	0	500	ns
t _V	SO output valid time		100	ns
t _{HO}	SO output hold time	0		ns
t _{RO}	SO output rise time		50	ns
t _{FO}	SO output fall time		50	ns
t _{HOLD}	HOLD time	400		ns
t _{HSU}	HOLD setup time	50		ns
t _{HH}	HOLD hold time	50		ns
t _{HZ}	HOLD low to output in high Z		100	ns
t _{LZ} HOLD high to output in low Z			100	ns
T _I Noise suppression time constant at SI, SCK, HOLD and CS inputs			20	ns
t _{CS}		100		ns
twpasu	WP, A0, A1 setup time	0		ns
t _{WPAH}	WP, A0, A1 hold time	0		ns

HIGH-VOLTAGE WRITE CYCLE TIMING

Symbol	Parameter	Тур.	Max.	Units
t _{WR}	High-voltage write cycle time (store instructions)	5	10	ms

XDCP TIMING

Symbol	Parameter		Max.	Units
t _{WRPO}	Wiper response time after the third (last) power supply is stable	5	10	μs
t _{WRL}	Wiper response time after instruction issued (all load instructions)	5	10	μs

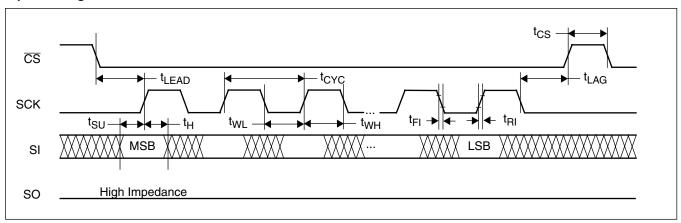
SYMBOL TABLE

WAVEFORM	INPUTS	OUTPUTS
	Must be steady	Will be steady
	May change from Low to High	Will change from Low to High
	May change from High to Low	Will change from High to Low
	Don't Care: Changes Allowed	Changing: State Not Known
	N/A	Center Line is High Impedance

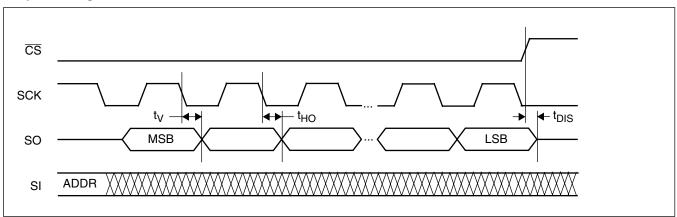
Characteristics subject to change without notice. 14 of 21

TIMING DIAGRAMS

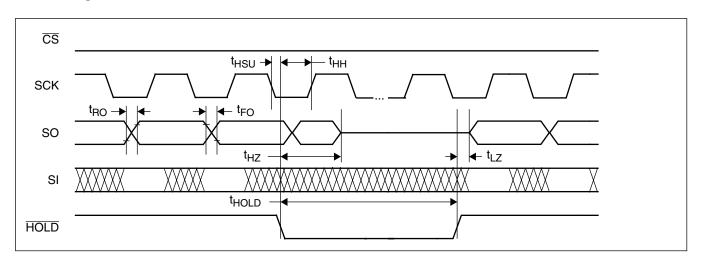
Input Timing



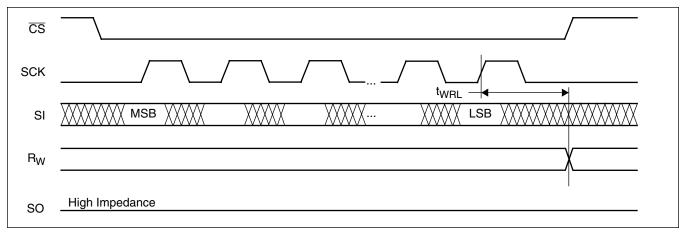
Output Timing



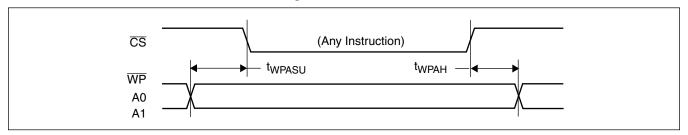
Hold Timing



XDCP Timing (for All Load Instructions)



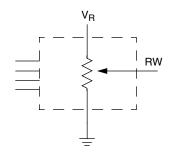
Write Protect and Device Address Pins Timing



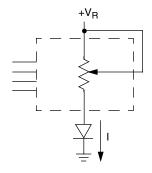
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APPLICATIONS INFORMATION

Basic Configurations of Electronic Potentiometers



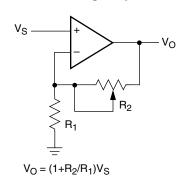
Three terminal Potentiometer; Variable voltage divider



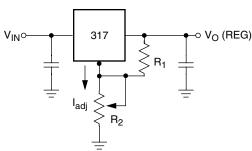
Two terminal Variable Resistor; Variable current

Application Circuits

Noninverting Amplifier

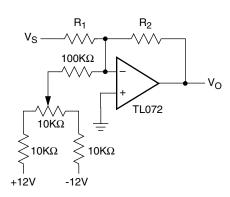


Voltage Regulator

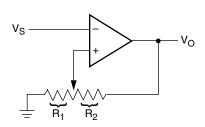


 $V_O (REG) = 1.25V (1+R_2/R_1)+I_{adj} R_2$

Offset Voltage Adjustment



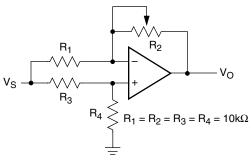
Comparator with Hysterisis



 $\begin{aligned} &V_{UL} = \{R_1/(R_1 + R_2)\} \ V_O(max) \\ &RL_L = \{R_1/(R_1 + R_2)\} \ V_O(min) \end{aligned}$

Application Circuits (Continued)

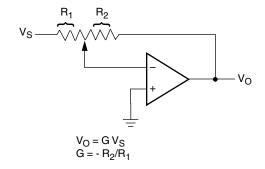
Attenuator



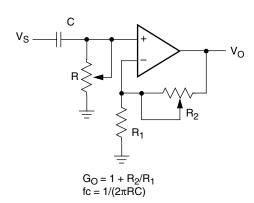
$$V_O = G V_S$$

-1/2 \le G \le +1/2

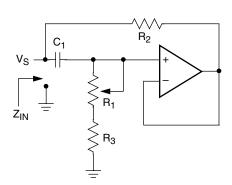
Inverting Amplifier



Filter

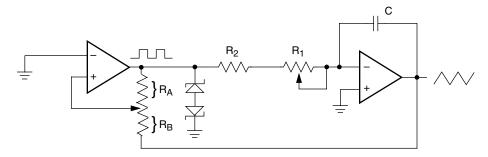


Equivalent L-R Circuit



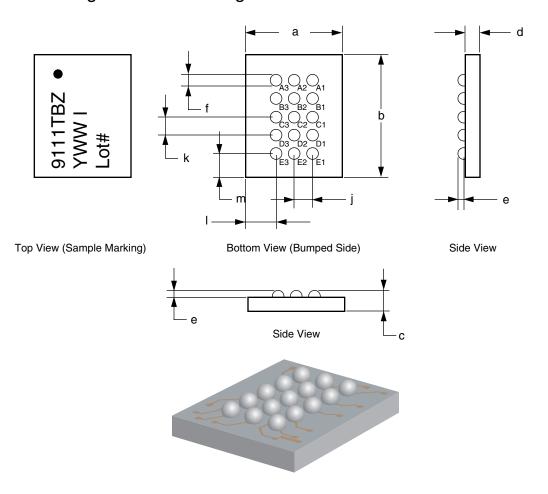
$$\begin{split} Z_{IN} = R_2 + s \; R_2 \; (R_1 + R_3) \; C_1 = R_2 + s \; \text{Leq} \\ (R_1 + R_3) >> R_2 \end{split}$$

Function Generator



 $\begin{aligned} &\text{frequency} & \propto R_1,\,R_2,\,C \\ &\text{amplitude} & \propto R_A,\,R_B \end{aligned}$

15-Bump Chip Scale Package (CSP B15) Package Outline Drawing



Package Dimensions

		Millimeters		
	Symbol	Min	Nominal	Max
Package Width	а	2.535	2.565	2.595
Package Length	b	3.272	3.302	3.332
Package Height	С	0.644	0.677	0.710
Body Thickness	d	0.444	0.457	0.470
Ball Height	е	0.200	0.220	0.240
Ball Diameter	f	0.300	0.320	0.340
Ball Pitch - Width	j		0.5	
Ball Pitch - Length	k		0.5	
Ball to Edge Spacing – Width	I	0.758	0.783	0.808
Ball to Edge Spacing - Length	m	0.626	0.651	0.676

Ball Matrix

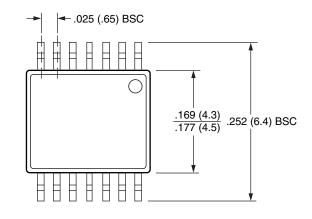
	3	2	1
Α	SO	Vcc	R_{L}
В	A0	NC*	R _H
С	CS	NC*	R _W
D	SCK	WP	HOLD
E	SI	Vss	A1

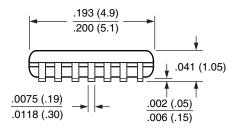
Characteristics subject to change without notice.

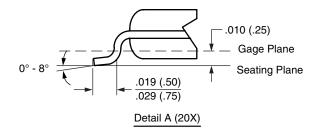
^{*} True no-connect bump

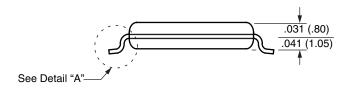
PACKAGING INFORMATION

14-Lead Plastic, TSSOP, Package Code V14



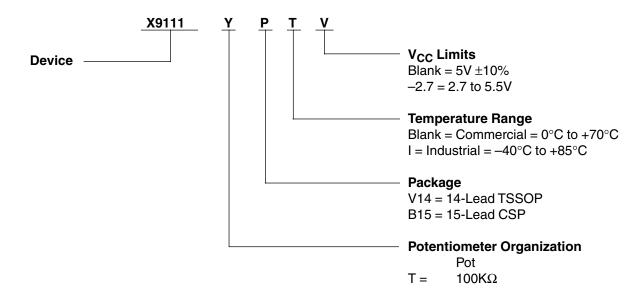






NOTE: ALL DIMENSIONS IN INCHES (IN PARENTHESES IN MILLIMETERS)

ORDERING INFORMATION



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